

electronically connectable thereto the substrate defining a seating surface for receiving the electronic circuit in seating engagement thereon, the seating surface having at least a first indent coated with an electrically conductive material, an improvement of a connector for electrically connecting the electronic circuit component in affixed engagement with the substrate, said connector comprising:

5 at least a first pin member affixed to the electrical circuit component to form a portion thereof, said first pin member of an electrically-conductive material that exhibits physical-memory characteristics, said first pin member positionable at least alternately in a first configuration and a memory configuration, said first pin member extending into the first indent when the electronic circuit is seated upon the seating surface and said first pin member is
10 molded in the first configuration, said first pin member reconfigured into the memory configuration responsive to heating to a deformation threshold temperature such that, when positioned in the memory configuration, first clutching forces exerted by said first pin member cause flexing engagement of said first pin member with the electrically conductive material coating the first indent.

15 3. (Amended) In the electronic circuit component of claim 1 wherein the at least the first indent comprises the first indent and at least a second indent, the improvement of the connector, said connector further comprising at least a second pin member, said first pin member extending into the first indent and said second pin member extending into the second indent when the electronic circuit component is sealed at the seating surface.

20 4. (Amended) In the electronic circuit component of claim 3, the improvement of the

connector, and wherein said second pin member is also positionable at least alternately in the first configuration and the memory configuration, said second pin member molded in the first configuration when the electronic circuit is seated upon the seating surface, said second pin member reconfigured into the memory configuration responsive to heating to a deformation threshold temperature such that, when positioned in the memory configuration second clutching forces exerted by said second pin member cause flexing engagement of said second pin member with electrically conductive material coating the second indent.

5 5. (Amended) In the electronic circuit component of claim 4, the improvement of the connector and wherein said first pin member is affixed to extend beneath a first side edge of the electronic circuit component, wherein said second pin member is affixed to extend beneath a second said edge of the electronic circuit component, and wherein the first clutching force and the second clutching force are exerted in opposing directions.

10 7. (Amended) In the electronic circuit component of claim 1, the improvement of the connector, and wherein said first pin member comprises an elongated camber-leg which exhibits a cambered-configuration when configured in the memory configuration.

15 8. (Amended) In the electronic circuit component of claim 7, the improvement of the connector, and wherein the elongated camber-leg forming said first pin member exhibits an amount of camber when configured in the memory configuration greater than when the elongated camber-leg forming said first pin member is configured in the first configuration.

20 9. (Amended) In the electronic circuit component of claim 1 wherein the at least the first

indent formed in the substrate is defined by a first through hole formed to extend therethrough, the improvement of the connector and wherein said first pin member extends through the first through hole when the electronic circuit component is seated at the seating surface.

10. (Amended) In the electronic circuit of claim 9, the improvement of the connector
5 and wherein said first pin member defines a proximal side portion affixed to the electronic circuit component and a distal side portion extending beyond the substrate when the electronic circuit component is seated upon the substrate.

11. (Amended) In the electronic circuit component of claim 10, a further improvement
10 of the connector and wherein said first pin member further comprises a foot piece positionable to abut against a bottom face surface of the substrate when said first pin member is configured in the memory configuration and the electronic circuit component is seated upon the seating surface, thereby to prevent removal of the electronic circuit component out of the seating surface.

12. (Amended) In the electronic circuit component of claim 11 the improvement of the
15 connector and wherein, when the electronic component is seated upon the seating surface, said first pin member extends through the first through hole when said first pin member is configured in the first configuration, said first pin member of diametrical dimensions preventing translation of said first pin member out of the first through hole subsequent to positioning of the electronic circuit component upon the seating surface and configuring said first pin member into the memory configuration.